

CLAIMS

1. A method for manufacturing an electronic device apparatus, the method comprising:

5 a step A of preparing a laminated product including a support and an electronic device fixed on the support;

a step B of preparing a resin sheet for sealing containing an alumina and a secondary aggregate formed by aggregating thermally anisotropic boron nitride crystals,
10 in which thermal conductivity differs depending on a direction, so as to be isotropic;

a step C of disposing the resin sheet for sealing on the electronic device of the laminated product;

a step D of embedding the electronic device into the
15 resin sheet for sealing; and

a step E of, after the step D, heating the resin sheet for sealing while maintaining the laminated product and the resin sheet for sealing in a pressurized state in a direction in which the laminated product and the resin
20 sheet for sealing are moved closer to each other, to subject the resin sheet for sealing to primary thermal curing.

2. The method for manufacturing an electronic device apparatus according to claim 1, wherein the step E includes a condition in which the thermal conductivity is 0.8 or more when the thermal conductivity of the resin sheet for
5 sealing after being thermally cured at a temperature of 150°C under pressure of 3 MPa for 1 hour is defined as 1.